

UltraVt[®] Depletion-Mode Power MOSFET

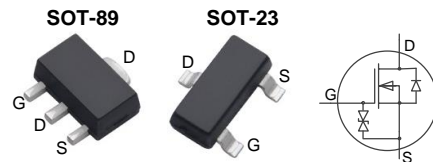
General Features

- ESD Improved Capability
- Depletion Mode (Normally On)
- Proprietary Advanced Planar Technology
- Proprietary Advanced Ultrahigh V_{th} Technology
- RoHS Compliant
- Halogen-free Available

BV _{DSX}	V _{GS(off)}	I _{DSS,min}
130V	-13V to -20V	100mA

Applications

- Quick Charger
- Current Source
- Voltage Source
- Type-C/PD charger



General Description

This novel depletion mode MOSFET, developed and manufactured by ARK proprietary UltraVt[®] technology. It has a high threshold voltage. By using the sub threshold characteristics, the depletion mode MOSFET can provide stably power to the load, and the voltage can be clamped to protect the load without Zener diode, and the circuit consumption is reduced.

Ordering Information

Part Number	Package	Marking	Remark
DMZ1315EL	SOT-23	1315L	Halogen Free
DMX1315EL	SOT-89	1315L	Halogen Free

Absolute Maximum Ratings

T_A=25°C unless otherwise specified

Symbol	Parameter	DMZ1315EL	DMX1315EL	Unit
V _{DSX}	Drain-to-Source Voltage ^[1]	130		V
I _D	Continuous Drain Current	0.1		A
I _{DM}	Pulsed Drain Current ^[2]	0.4		
P _D	Power Dissipation	0.5	1.0	W
V _{GS}	Gate-to-Source Voltage	±30		V
V _{ESD}	Gate to Source ESD ^[3]	700		V
	Source to Gate ESD ^[3]	700		V
T _L	Soldering Temperature Distance of 1.6mm from case for 10 seconds	300		°C
T _J and T _{STG}	Operating and Storage Temperature Range	-55 to 150		

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

Thermal Characteristics

Symbol	Parameter	DMZ1315EL	DMX1315EL	Unit
R _{θJA}	Thermal Resistance, Junction-to-Ambient	250	125	K/W

Electrical Characteristics
OFF Characteristics
 $T_A = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
BV_{DSX}	Drain-to-Source Breakdown Voltage	130	--	--	V	$V_{GS} = -30\text{V}$, $I_D = 1\text{mA}$
$I_{D(OFF)}$	Drain-to-Source Leakage Current	--	--	10	μA	$V_{DS} = 130\text{V}$, $V_{GS} = -30\text{V}$
I_{GSS}	Gate-to-Source Leakage Current	--	--	20	μA	$V_{GS} = +30\text{V}$, $V_{DS} = 0\text{V}$
		--	--	-20		$V_{GS} = -30\text{V}$, $V_{DS} = 0\text{V}$

ON Characteristics
 $T_A = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
I_{DSS}	Saturated Drain-to-Source Current	100	--	--	mA	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance	--	15	30	Ω	$V_{GS} = 0\text{V}$, $I_D = 50\text{mA}$ ^[4]
$V_{GS(OFF)}$	Gate-to-Source Cut-off Voltage	-13	--	-20	V	$V_{DS} = 9\text{V}$, $I_D = 8\mu\text{A}$

Source-Drain Diode Characteristics
 $T_A = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min	Typ.	Max.	Units	Test Conditions
V_{SD}	Diode Forward Voltage	--	--	1.2	V	$I_{SD} = 100\text{mA}$, $V_{GS} = -30\text{V}$

NOTE:

 [1] $T_J = +25^\circ\text{C}$ to $+150^\circ\text{C}$

[2] Repetitive rating, pulse width limited by maximum junction temperature.

[3] The test is based on JEDEC EIA/JESD22-A114 (HBM).

 [4] Pulse width $\leq 380\mu\text{s}$; duty cycle $\leq 2\%$.

Typical and highlight Characteristics

DMZ1315EL/DMX1315EL is an UltraVt[®] depletion mode MOS device. A stable output voltage source or current source is implemented by using the sub-threshold characteristics of the device. Its basic application is shown as Figure 1:

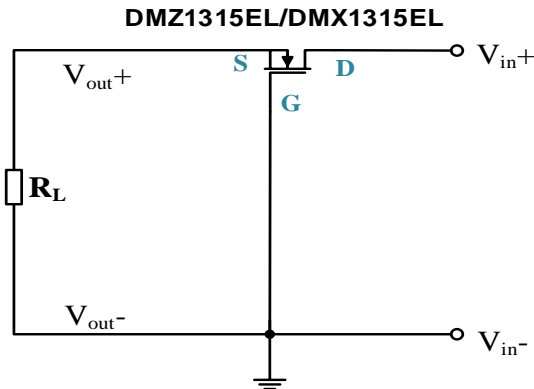
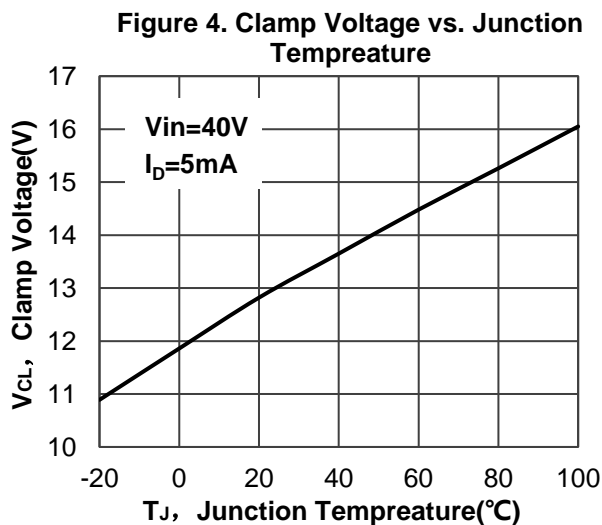
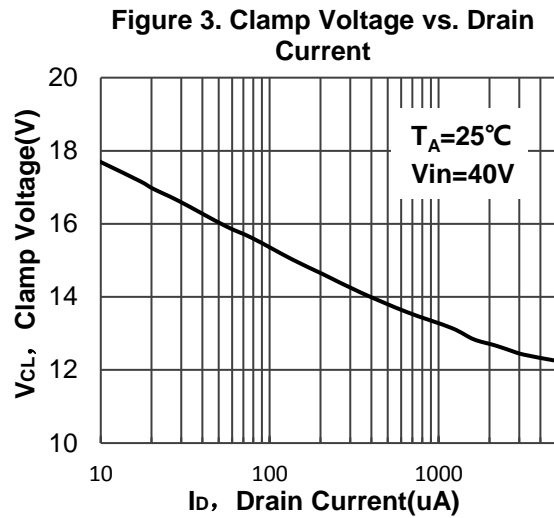
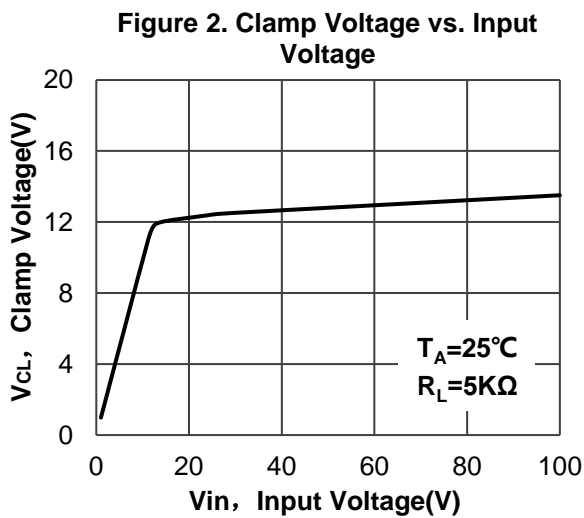


Figure1. Drain Current I_D is decided by Load Resistance



Typical Application

In the QC2.0/3.0 and Type-C/PD charger circuits, using DMZ1315EL/DMX1315EL as a high voltage linear regulators can make the PWM IC power supply circuit more simplified, as shown below:

In Figure 5, the transistor Q is used to provide power, and the zener diode Z is used to clamp voltage, the power supply circuit of IC is composed of several components.

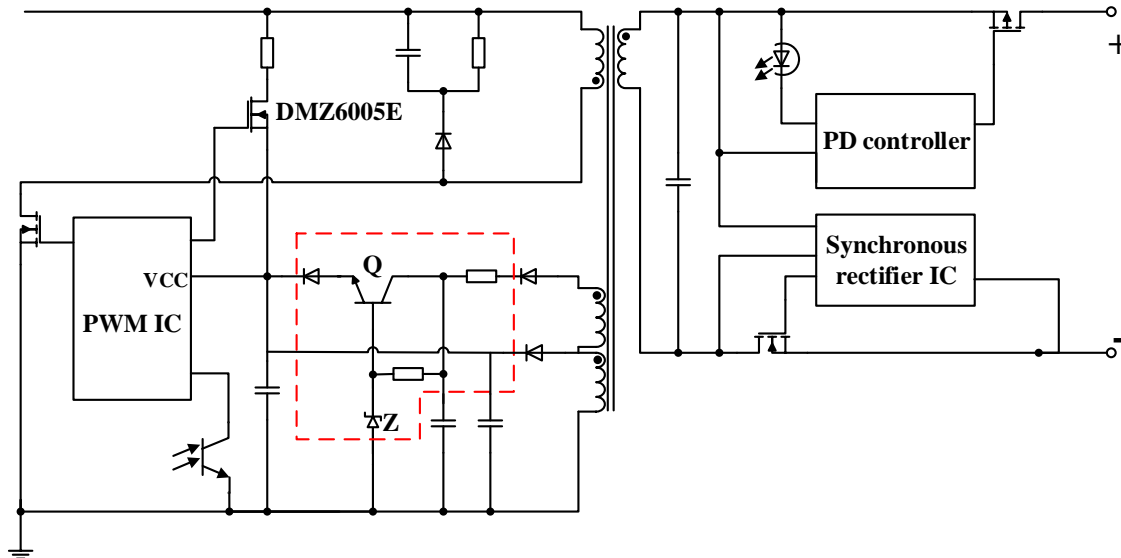


Figure 5. Normal Circuit with Transistor and Diode

In Figure 6, providing power and clamp voltage use only one device—DMZ1315EL/DMX1315EL, the circuit is simplified.

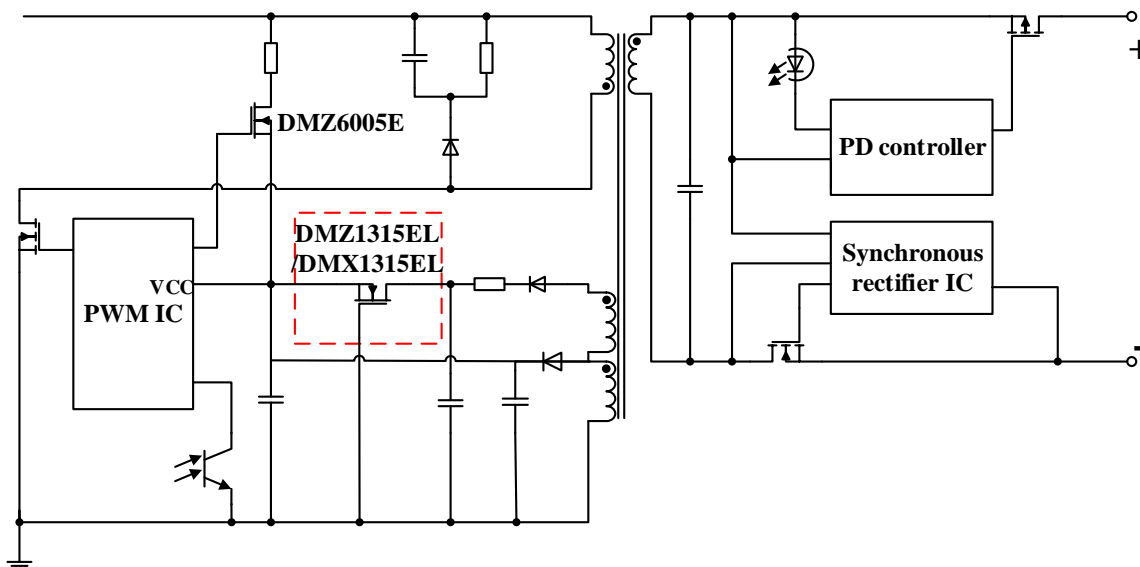


Figure 6. Circuit with DMZ1315EL/DMX1315EL

From the above function, we can see the depletion mode MOSFET operate in sub-threshold region, the V_{out} is always below or closed to the threshold voltage or Gate-to-Source Cut-off Voltage $V_{GS(OFF)}$, no matter how the input voltage V_{in} changes. Therefore, in addition to provide power for load like IC, the output voltage V_{out} can be clamped to the $V_{GS(OFF)}$, the IC is then protected from variable voltage or current. DMZ1315EL/DMX1315EL can support up to 130V input voltage. V_{out} and V_{in} have relations following the formulas:



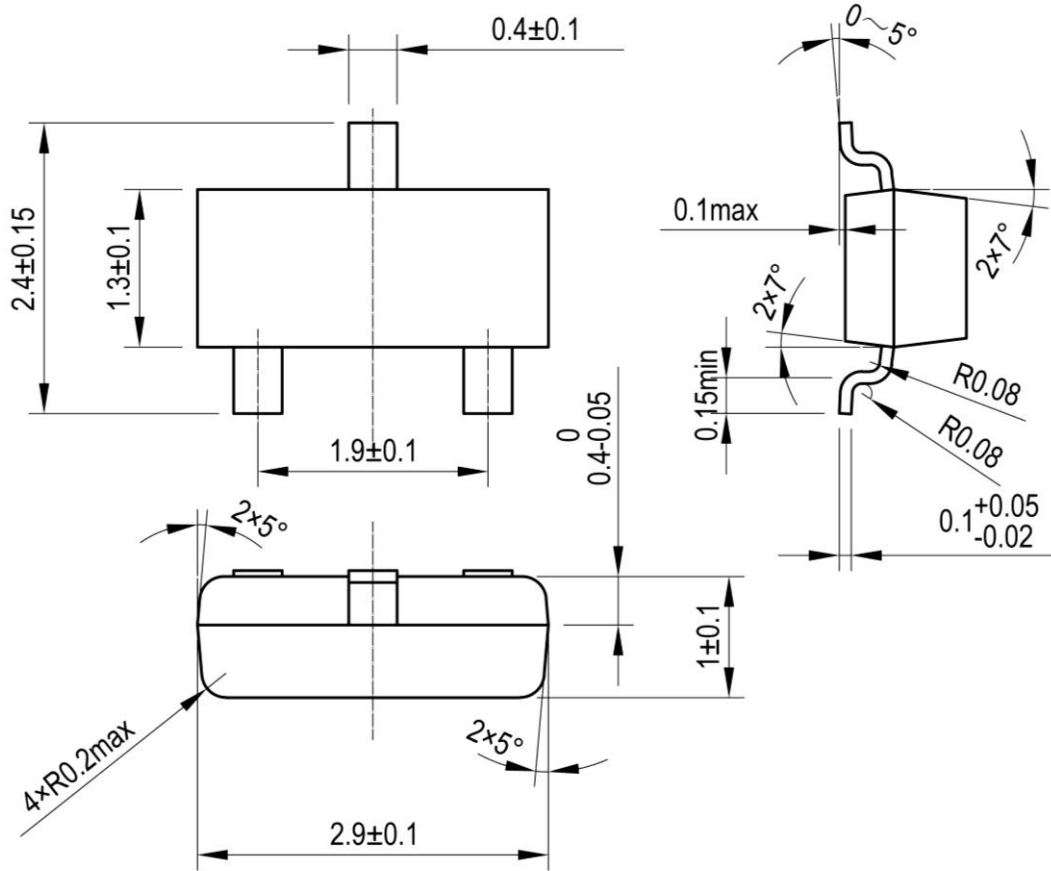
If $V_{in} < |V_{GS(OFF)}|$, then $V_{out} \approx V_{in}$

If $V_{in} \geq |V_{GS(OFF)}|$, then $V_{out} \leq |V_{GS(OFF)}|$

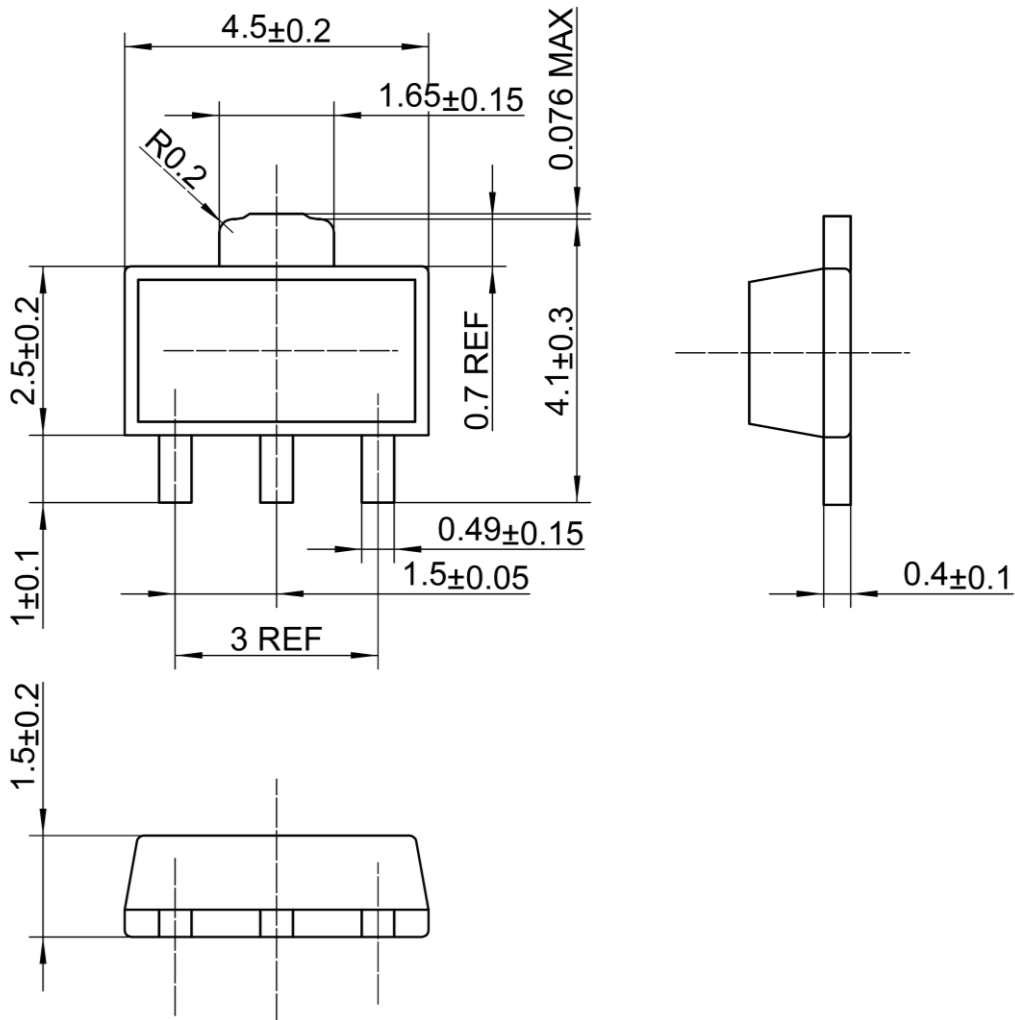
The Ultrahigh V_{th} Depletion Mode Power MOSFET--DMZ1315EL/DMX1315EL, was developed by ARK Microelectronics proprietary and patent technology. The threshold voltage $V_{GS(OFF)}$ of DMZ1315EL/DMX1315EL is between -13V and -20V, can provide sufficient voltage for load such like a PWM IC in the primary side of a Flyback converter.

Package Dimensions

SOT-23



SOT-89





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